

TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

**TC74HC367AP, TC74HC367AF, TC74HC367AFN  
TC74HC368AP, TC74HC368AF, TC74HC368AFN****HEX BUS BUFFER**TC74HC367AP / AF / AFN NON-INVERTED (3-STATE)  
TC74HC368AP / AF / AFN INVERTED (3-STATE)

The TC74HC367A and TC74HC368A are high speed CMOS 3-STATE BUS BUFFERS fabricated with silicon gate C<sup>2</sup>MOS technology.

They achieve the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

They contain six buffers; four buffers are controlled by an enable input ( $\bar{G}_1$ ), and the other two buffers are controlled by another enable input ( $\bar{G}_2$ ). The outputs of each buffer group are enabled when  $\bar{G}_1$  and/or  $\bar{G}_2$  inputs are held low; if held high, these outputs are in a high impedance state.

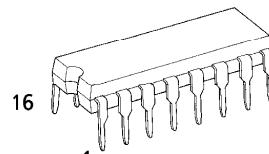
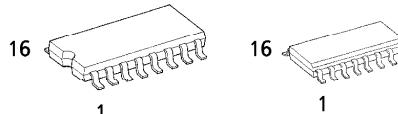
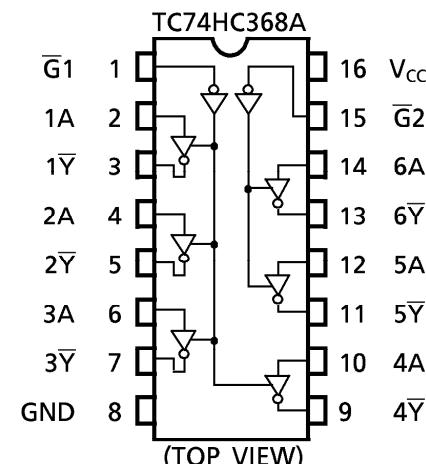
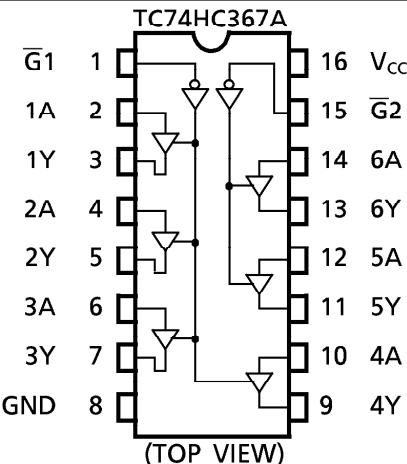
The TC74HC367A is a non-inverting output type, while the TC74HC368A is an inverting output type.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

**FEATURES:**

- High Speed..... $t_{pd} = 11\text{ns}(\text{typ.})$  at  $V_{CC} = 5\text{V}$
- Low Power Dissipation..... $I_{CC} = 4\mu\text{A}(\text{Max.})$  at  $T_a = 25^\circ\text{C}$
- High Noise Immunity..... $V_{NIH} = V_{NIL} = 28\% V_{CC}$  (Min.)
- Output Drive Capability..... 15 LSTTL Loads
- Symmetrical Output Impedance.....  $|I_{OH}| = I_{OL} = 6\text{mA}$
- Balanced Propagation Delays.....  $t_{PLH} \approx t_{PHL}$
- Wide Operating Voltage Range.....  $V_{CC}$  (opr.) = 2V ~ 6V
- Pin and Function Compatible with 74LS367/368

(Note) The JEDEC SOP (FN) is not available in Japan.

P (DIP16-P-300-2.54A)  
Weight : 1.00g (Typ.)F (SOP16-P-300-1.27) FN (SOL16-P-150-1.27)  
Weight : 0.18g (Typ.) Weight : 0.13g (Typ.)**PIN ASSIGNMENT****TRUTH TABLE**

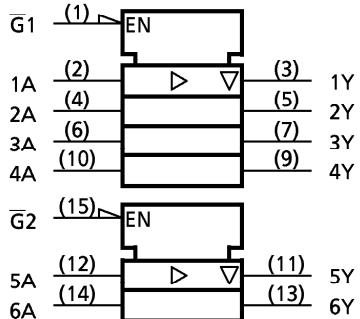
INPUTS		OUTPUTS	
$\bar{G}$	An	$Y(367A)$	$\bar{Y}(368A)$
L	L	L	H
L	H	H	L
H	X	Z	Z

X : Don't Care, Z : High Impedance

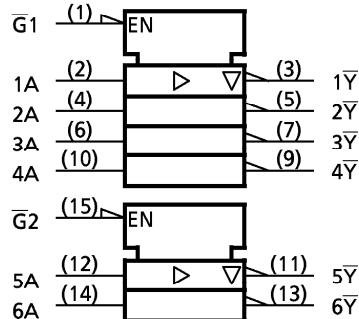
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## IEC LOGIC SYMBOL

TC74HC367A

HEX BUS BUFFER  
(3 - STATE)

TC74HC368A

HEX BUS BUFFER  
(3 - STATE / INV.)

961001EBA2'

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## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	$V_{CC}$	-0.5~7	V
DC Input Voltage	$V_{IN}$	-0.5~ $V_{CC} + 0.5$	V
DC Output Voltage	$V_{OUT}$	-0.5~ $V_{CC} + 0.5$	V
Input Diode Current	$I_{IK}$	$\pm 20$	mA
Output Diode Current	$I_{OK}$	$\pm 20$	mA
DC Output Current	$I_{OUT}$	$\pm 35$	mA
DC $V_{CC}$ /Ground Current	$I_{CC}$	$\pm 75$	mA
Power Dissipation	$P_D$	500 (DIP)* / 180 (SOP)	mW
Storage Temperature	$T_{STG}$	-65~150	°C

\*500mW in the range of  $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$ . From  $T_a = 65^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  a derating factor of  $-10\text{mW}/^{\circ}\text{C}$  shall be applied until 300mW.

## RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	$V_{CC}$	2~6	V
Input Voltage	$V_{IN}$	0~ $V_{CC}$	V
Output Voltage	$V_{OUT}$	0~ $V_{CC}$	V
Operating Temperature	$T_{Opr}$	-40~85	°C
Input Rise and Fall Time	$t_r, t_f$	0~ 1000 ( $V_{CC} = 2.0\text{V}$ ) 0~ 500 ( $V_{CC} = 4.5\text{V}$ ) 0~ 400 ( $V_{CC} = 6.0\text{V}$ )	ns

## DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	$V_{CC}$ (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	$V_{IH}$		2.0 4.5 6.0	1.50 3.15 4.20	— — —	— — —	1.50 3.15 4.20	— — —	V
Low - Level Input Voltage	$V_{IL}$		2.0 4.5 6.0	— — —	— — —	0.50 1.35 1.80	— — —	0.50 1.35 1.80	V
High - Level Output Voltage	$V_{OH}$	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OH} = -20\mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	2.0 4.5 6.0	— — —	1.9 4.4 5.9	V
			$I_{OH} = -6\text{ mA}$ $I_{OH} = -7.8\text{ mA}$	4.5 6.0	4.18 5.68	4.31 5.80	— —	4.13 5.63	
Low - Level Output Voltage	$V_{OL}$	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OL} = 20\mu\text{A}$	2.0 4.5 6.0	— — —	0.0 0.0 0.0	0.1 0.1 0.1	— — —	V
			$I_{OL} = 6\text{ mA}$ $I_{OL} = 7.8\text{ mA}$	4.5 6.0	— —	0.17 0.18	0.26 0.26	— —	
3 - State Output Off - State Current	$I_{OZ}$	$V_{IN} = V_{IH}$ or $V_{IL}$ $V_{OUT} = V_{CC}$ or GND	6.0	—	—	$\pm 0.5$	—	$\pm 5.0$	$\mu\text{A}$
Input Leakage Current	$I_{IN}$	$V_{IN} = V_{CC}$ or GND	6.0	—	—	$\pm 0.1$	—	$\pm 1.0$	
Quiescent Supply Current	$I_{CC}$	$V_{IN} = V_{CC}$ or GND	6.0	—	—	4.0	—	40.0	

AC ELECTRICAL CHARACTERISTICS (Input  $t_r = t_f = 6\text{ns}$ )

PARAMETER	SYMBOL	TEST CONDITION	CL	$V_{CC}(\text{V})$	Ta = 25°C			Ta = -40~85°C		UNIT
					MIN.	TYP.	MAX.	MIN.	MAX.	
Output Transition Time	$t_{TLH}$ $t_{THL}$		50	2.0 4.5 6.0	— — —	25 7 6	60 12 10	— — —	75 15 13	ns
Propagation Delay Time	$t_{PLH}$ $t_{PHL}$		50	2.0 4.5 6.0	— — —	36 12 10	95 19 16	— — —	120 24 20	
			150	2.0 4.5 6.0	— — —	40 16 14	130 26 22	— — —	165 33 28	
			50	2.0 4.5 6.0	— — —	36 12 10	120 24 20	— — —	150 30 26	
	$t_{PZL}$ $t_{PZH}$	$R_L = 1\text{k}\Omega$	150	2.0 4.5 6.0	— — —	40 16 14	160 32 27	— — —	200 40 34	
Output Disable Time	$t_{PLZ}$ $t_{PHZ}$	$R_L = 1\text{k}\Omega$	50	2.0 4.5 6.0	— — —	35 15 13	120 24 20	— — —	150 30 26	
Input Capacitance	$C_{IN}$				—	5	10	—	10	pF
Output Capacitance	$C_{OUT}$				—	10	—	—	—	
Power Dissipation Capacitance	$C_{PD}$ (1)	TC74HC367A			—	36	—	—	—	
		TC74HC368A			—	30	—	—	—	

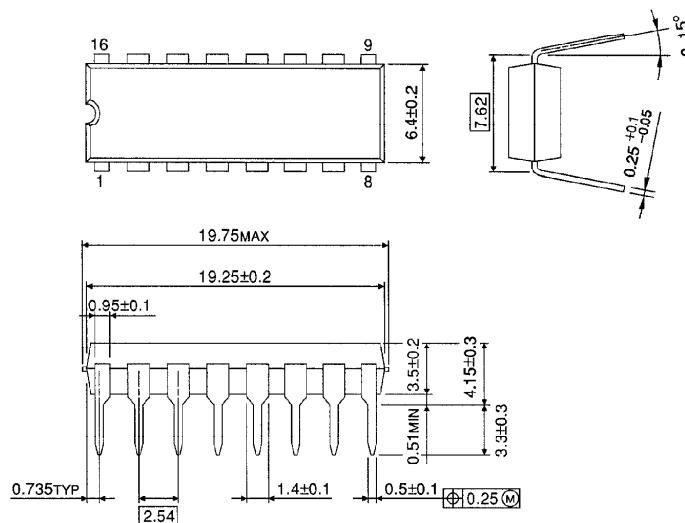
Note (1)  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

$$I_{CC(\text{opr})} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/6 \text{ (per bit)}$$

## DIP 16PIN OUTLINE DRAWING (DIP16-P-300-2.54A)

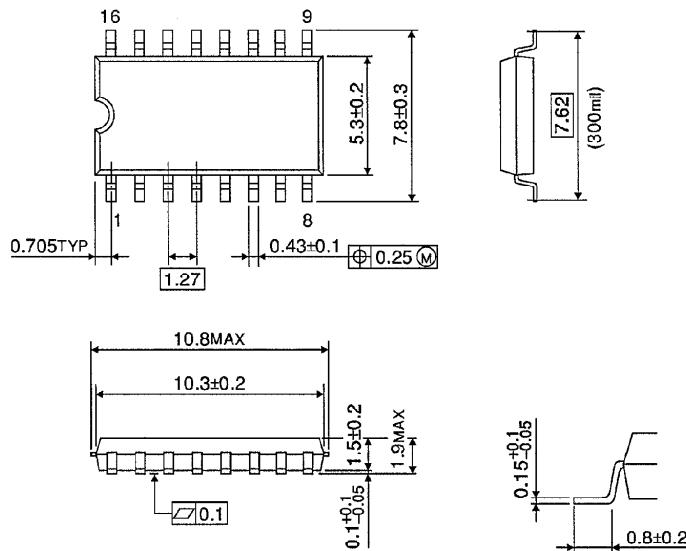
Unit in mm



Weight : 1.00g (Typ.)

## SOP 16PIN (200mil BODY) OUTLINE DRAWING (SOP16-P-300-1.27)

Unit in mm

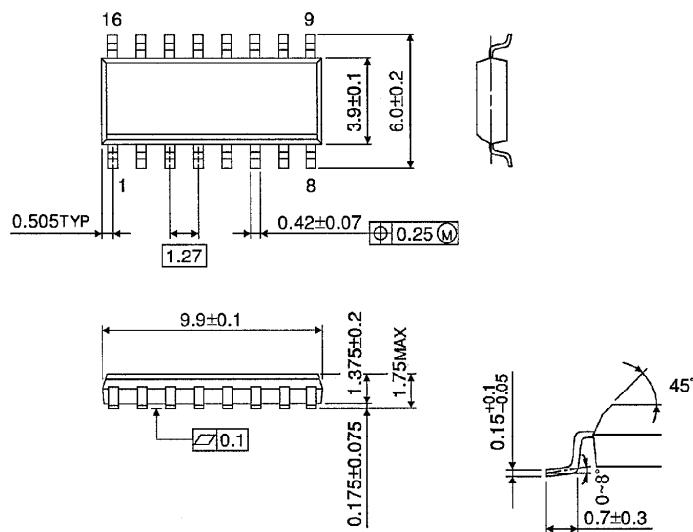


Weight : 0.18g (Typ.)

## SOP 16PIN (150mil BODY) OUTLINE DRAWING (SOL16-P-150 -1.27)

Unit in mm

(Note) This package is not available in Japan.



Weight : 0.13g (Typ.)